SuperBelle meeting, Dec. 12, 2008

Level I CDC trigger - mainly 3D tracking

Y. Iwasaki (KEK) and Eunil Won (Korea U)

✓ Fast trigger : within 3 - 3.5 usec

✓ Tight but efficient logic : S/N >> 0.1 , efficiency ~ 1.0

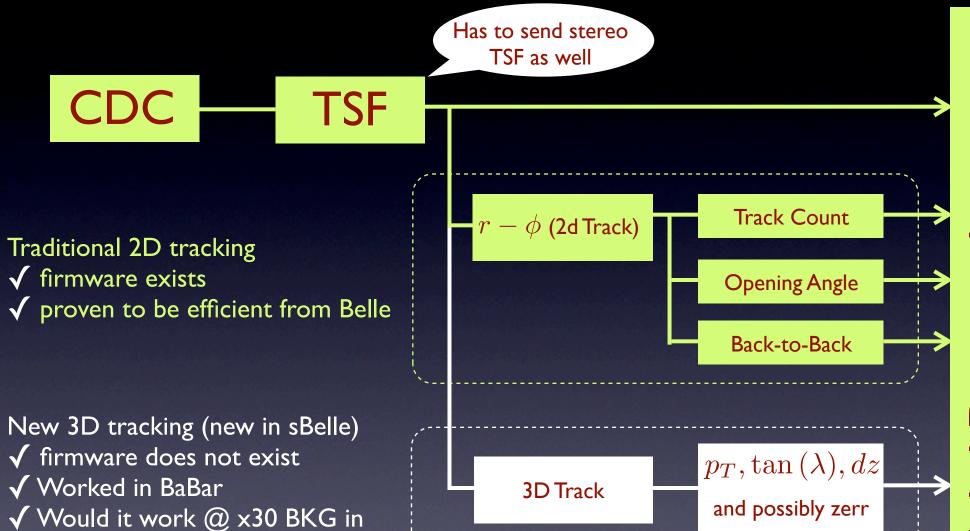
\checkmark Rate @ L = 8 × 10³⁵ /cm²/s

Average LI rate ~ 10 kHz, Maximum ~ 30 kHz (worst 100 kHz, see July meeting talk by Y. Iwasaki : so more sophisticated algorithm is needed)

✓ CDC specific charged track info : order 2000 bits to GDL

 \checkmark We have two strategies :2D and 3D tracking in LI

LI Track trigger outline



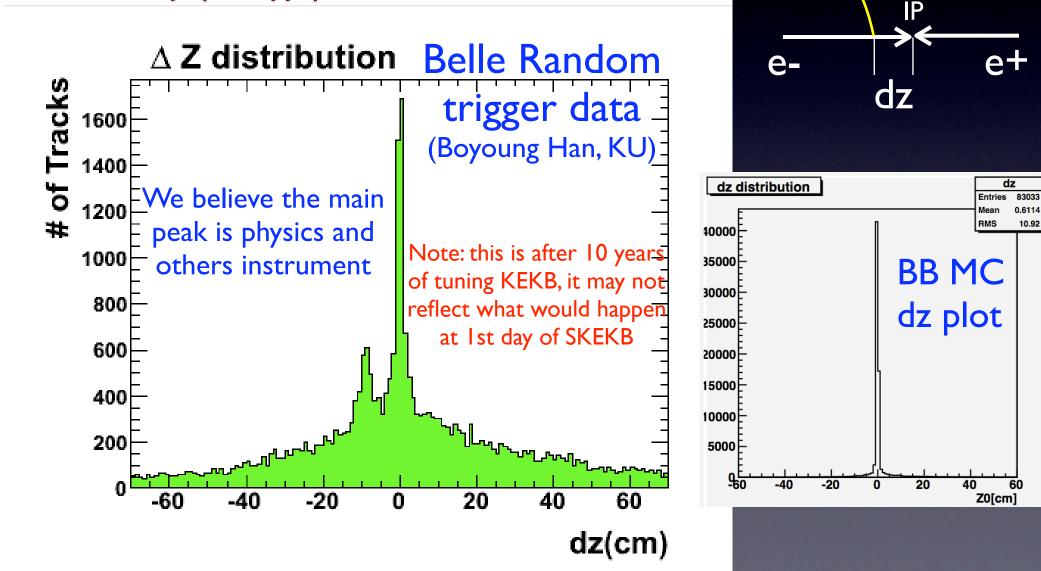
For both 2D and 3D, new hardware will be developed

given latency?

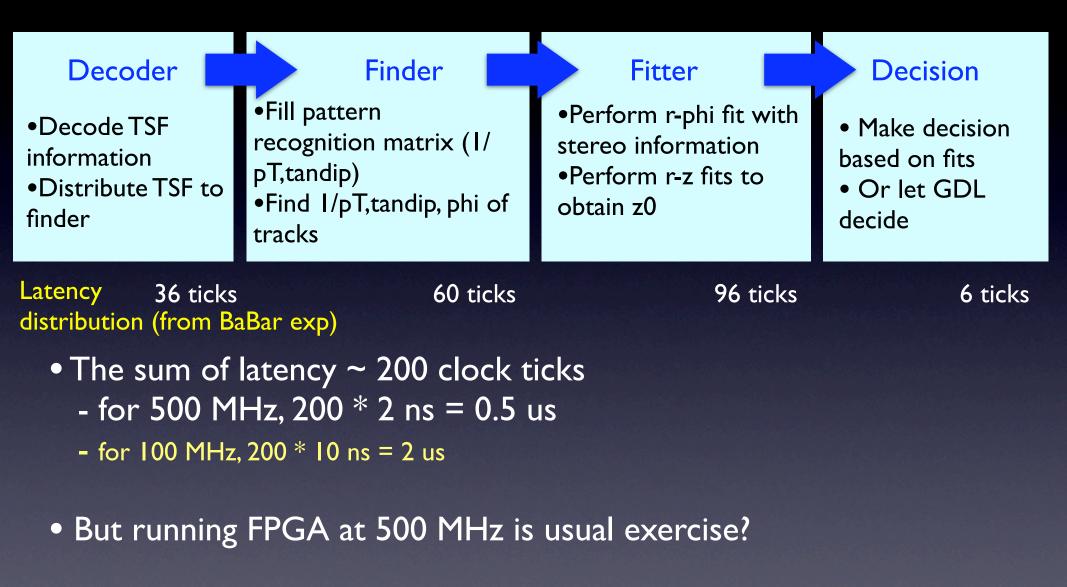
3D Track Triggering

Idea is not to trigger on events with large dz

track dz and pT(=1/kappa) distribution:



Outline of the 3D Algorithm



• Would this algorithm fit in single FPGA?

- one board houses one FPGA covering 1/8 of full CDC volume

Latency Friction

Trigger group

Sophisticated trigger is desired
5 us seems their favorite number (BaBar : 12 us) but 3.5 us is OK?

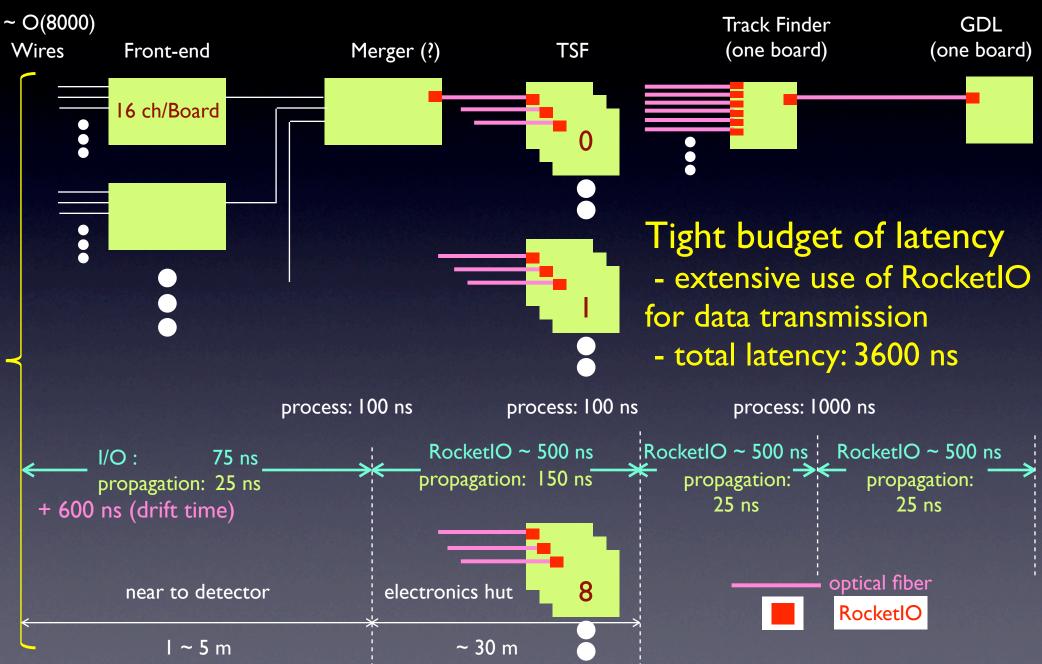
DAQ group

Minimum dead-time is desired
~ 3% seems their limit (Correct me if I am wrong)
Not only latency, but also time for two consecutive L1 triggers
At least now they know situation with SVD

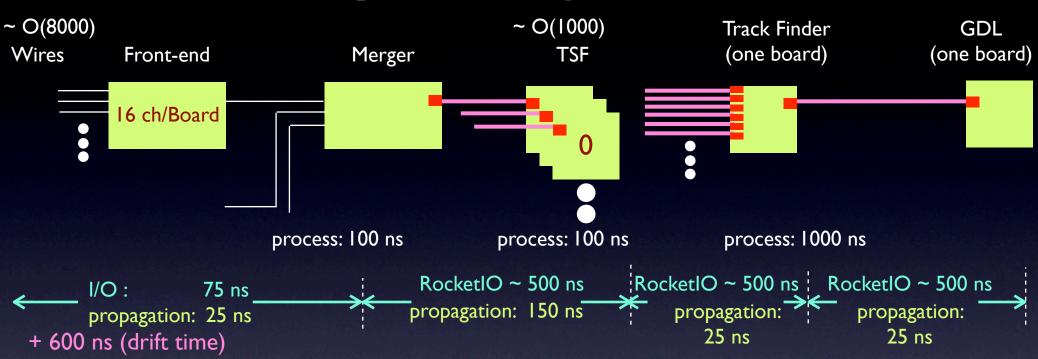
Largely it is 3D triggers that generates this friction (so it is me)

Detailed discussion on the latency : DAQ session

Trigger lines for CDC



Latency Budget for 3D



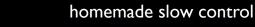
• The assumption of 0.5 us from RocketIO realistic? (will be measured)

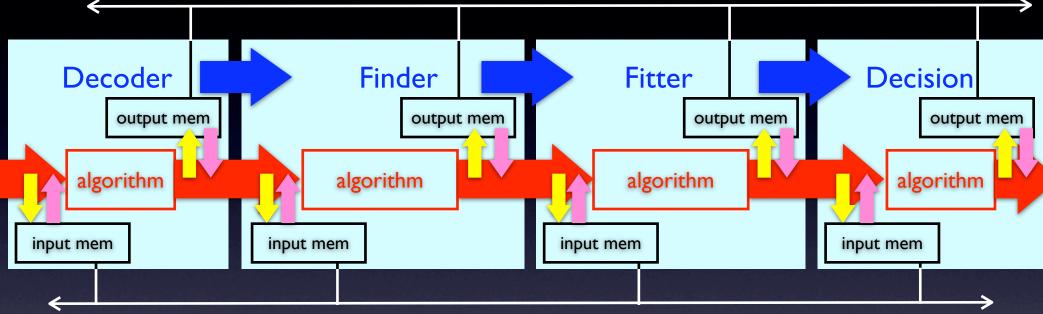
• The 3.6 us latency scenario: we are left with 1 us in the beginning

For 3D tracking, I.0 us maybe "OK": w/ running @ 250 MHz = 200 + 50 (spare) ticks

A firmware design model (from BaBar)

• A "play-record" model





• The upstream "plays" data and input/output of module "record" data into memory

The recorded data can be readable/writable via homemade slow control
This has been tremendous help in developing/debugging the firmware in particular in a large scale VHDL coding

I'm thinking of something similar to this - we have VME access

Hardware Development Status

- TSF, TF (2D), 3D fit board, and GDL will have all same form factor (VME 6U) : assuming RocketIO
- In total, O(25) is needed
- Hardware design status is same as in GDL case (see Y. Iwasaki's talk)

Algorithm Development Status

- TSF firmware: exists
- 2D TF

✓ present algorithm can be used without modification
 ✓ "Half 3D tracking" : Hough transformation is under
 development (Y. Iwasaki)

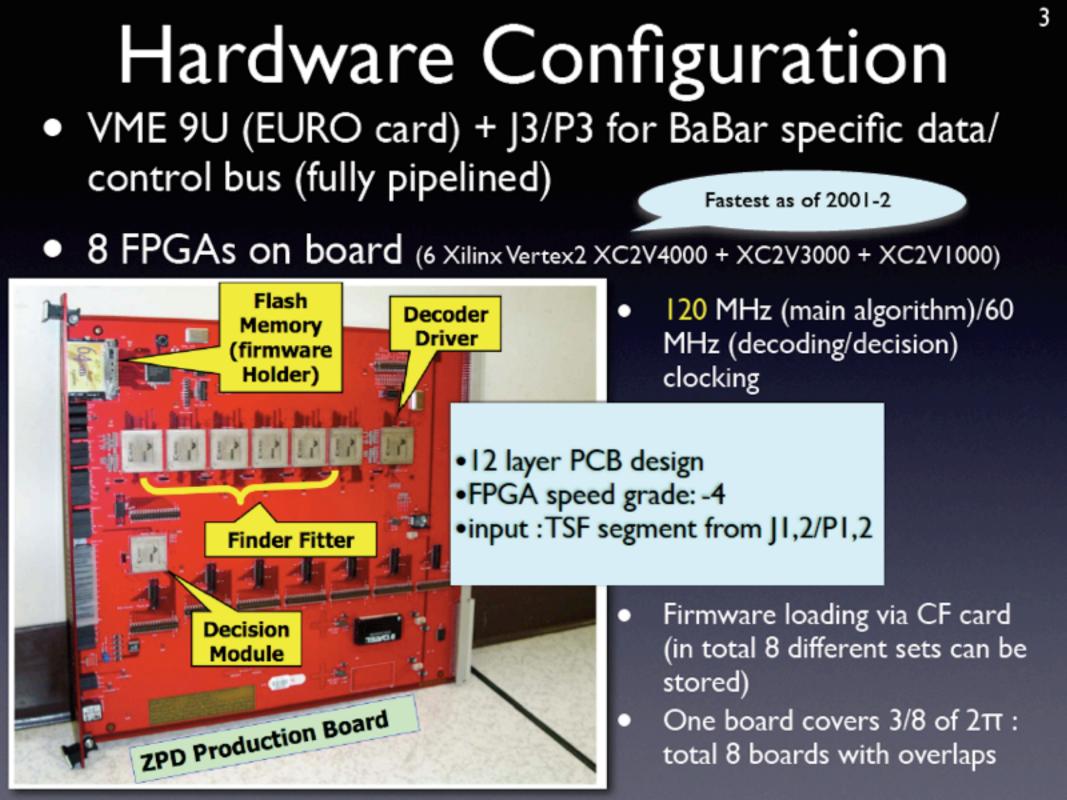
- 3D track trigger
 - \checkmark Just started in the framework of tsim-CDC
 - \checkmark A lot to be done (pattern recognition, finding and fitting)
- •
- GDL

 \checkmark A lot of parts can be reused (See Iwasaki's talk)

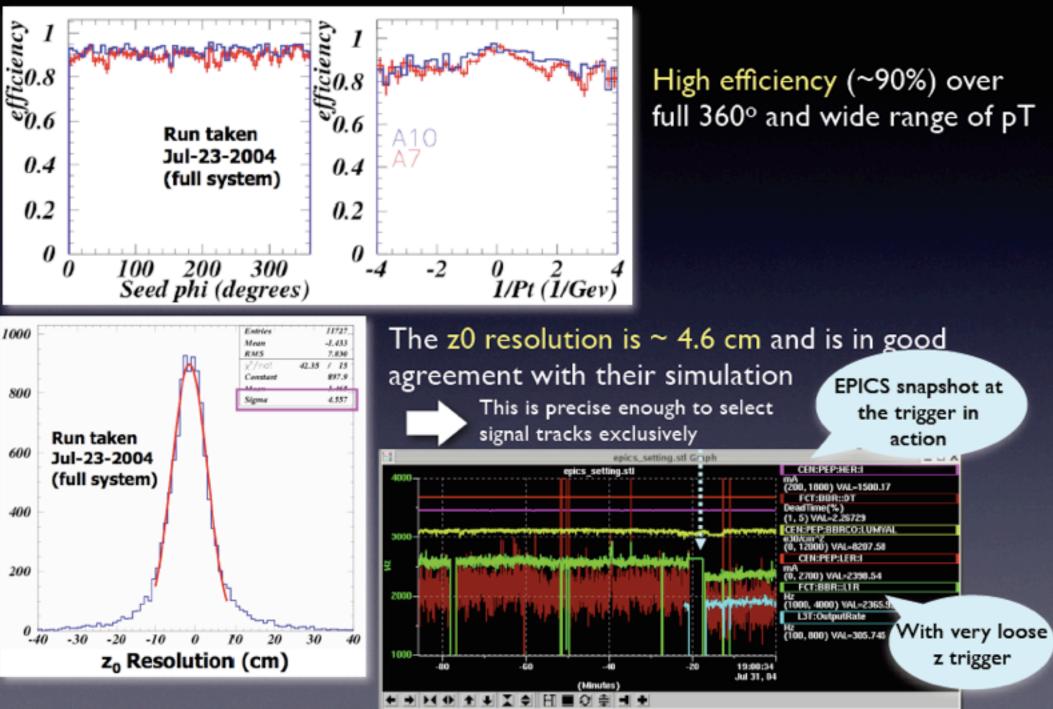
Summary/Issues

- Hardware in good progress
- Algorithm in good shape except 3D track triggers
- What do we do if the latency becomes problem?
- Will 3D work @ x30 BKG?

Backup Slides



Performance of BaBar 3D Track Trigger



Can we produce z0 in sBelle?

• BaBar has one board (has 8 FPGAs) for 1/8 of 2π

Flash

(firmware Holder)	Decoder			
	Model	Function	CLB	Usage
Finder Fitter	XC2V4000	Finder and Fitter	23,040	44%
Decision	XC2V3000	Decoder and Driver	14,336	27%
Module	XC2V1000	Decision Module	5,120	70%
ZPD Production Boar	•			

Total 23040*6+14336+5120=1 60k (17.6k)

Grand total: 160k*8=1.2 M blocks (140k)

(weighted by usage: but place&route nontrivial if usage is high!)

 If we use Vertex5 (the lastest, largest, and fastest from Xilinx as far as I know. Does Altera have better ones?)

Model	CLB	
XC5VLX330	51,840	

No way we can fit into a single board

One board covering 1/8 may be OK (Note:TSFs are grouped in layers, not in phi)